ABSTRACT

SEMICONDUCTOR PACKAGE LEADFRAME ASSEMBLY AND METHOD OF MANUFACTURE

A semiconductor package and the leadframe therefor having a reverse-down set part formed in the tie bar supporting the chip paddle. The reverse-down set part of the tie bar may be formed by a mechanical stamping process in such a way that it is present within the insulating body, interlocking therewith. This feature also facilitates the prevention of a short circuit between the tie bar that is exposed externally from the package body and the exposed internal lead through solder upon the mounting of a semiconductor package onto a motherboard.

This Sheet Has Been Replaced

